

Variant: 001
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PMP9403 REV A Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	IPCBA1	1		PMP7850 RevB	Any	PMP7850 RevB PCB	N/A
2	C3	1	180uF	16SVP180MX	Sanyo	CAP, Al Electrolytic, 180uF, 16V, +/-20%, SMT	
3	C4, C5, C22, C23, Cx1, Cx4	6	220uF	63CE220KX	Sanyo	CAP, Al Electrolytic, 220uF, 63V, +/-20%, 0.14Ohm ESR, SMT	
4	C6, C7, C8, C9, C24, C25, C26, C27	8	10uF	CL31B106KAHNNNB	Samsung	CAP, CERM, 10uF, 25V, X7R, 10%, 1206	1206
5	C10, C28, Cx2, Cx3, Cx5, Cx6	6	3.3uF	GRM32DR71H335KA88L	Murata	CAP, CERM, 3.3uF, 50V, X7R, 10%, 1210	1210
6	C11, C13, C29, C31	4	0.47uF	GRM188R71E474KA12D	MuRata	CAP, CERM, 0.47uF, 25V, +/-10%, X7R, 0603	0603
7	C12, C30	2	100pF	GRM1885C1H101JA01D	MuRata	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	0603
8	C14, C32	2	4.7uF	GRM21BR71C475KA73L	MuRata	CAP, CERM, 4.7uF, 16V, +/-10%, X7R, 0805	0805
9	C15	1	0.22uF	GRM188R71E224KA88D	MuRata	CAP, CERM, 0.22uF, 25V, +/-10%, X7R, 0603	0603
10	C17	1	0.047uF	GRM188R71E473KA01D	MuRata	CAP, CERM, 0.047uF, 25V, +/-10%, X7R, 0603	0603
11	C18	1	330pF	06035A331JAT2A	AVX	CAP, CERM, 330pF, 50V, +/-5%, C0G/NP0, 0603	0603
12	C20	1	0.022uF	C0603C223K3RACTU	Kemet	CAP, CERM, 0.022uF, 25V, +/-10%, X7R, 0603	0603
13	C33	1	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0 ohm, 5%, 0.1W, 0603	0603
14	C34	1	0.01uF	GRM188R71C103KA01D	MuRata	CAP, CERM, 0.01uF, 16V, +/-10%, X7R, 0603	0603
15	D1, D3	2	0.57V	PMEG6010CEH,115	NXP Semiconductor	Diode, Schottky, 60V, 1A, SOD-123F	SOD-123F
16	D4, D5	2	0	CRCW12060000Z0EA	Vishay-Dale	RES, 0 ohm, 5%, 0.25W, 1206	1206
17	FID1, FID2, FID3	3	N/A	N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
18	IN1, OUT1, TP5, TP6	4	White	5002	Keystone	Test Point, TH, Miniature, White	Keystone5002
19	J1, J2, J3, J4	4		575-4	Keystone	Standard Banana Jack, Uninsulated, 5.5mm	Keystone_575-4
20	L1, L2	2	15uH	SER2918H-153KL	Coilcraft	Inductor, Shielded E Core, Ferrite, 15uH, 21.9A, 0.0026 ohm, SMD	SER2918
21	Q1, Q3, Q4, Q5, Q7, Q8	6	80V	BSC047N08NS3 G	Infineon Technologies	MOSFET, N-CH, 80V, 100A, PG-TDSON-8	PG-TDSON-8
22	R3, R24	2	0.004	PMR100HZPFV4L00	Rohm Semiconductor	RES, 0.004 ohm, 1%, 2W, 2512	2512
23	R4, R7, R13, R14, R15, R27, R30, R31, R32	9	0	ERJ-3GEY0R00V	Panasonic	RES, 0 ohm, 5%, 0.1W, 0603	0603
24	R5, R6, R25, R26	4	100	CRCW0603100RFKEA	Vishay-Dale	RES, 100 ohm, 1%, 0.1W, 0603	0603
25	R10	1	49.9k	CRCW060349K9FKEA	Vishay-Dale	RES, 49.9k ohm, 1%, 0.1W, 0603	0603
26	R11, R29	2	3.3	CRCW06033R30JNEA	Vishay-Dale	RES, 3.3 ohm, 5%, 0.1W, 0603	0603
27	R12	1	8.87k	CRCW06038K87FKEA	Vishay-Dale	RES, 8.87k ohm, 1%, 0.1W, 0603	0603
28	R16, R18, R21	3	51.1k	CRCW060351K1FKEA	Vishay-Dale	RES, 51.1k ohm, 1%, 0.1W, 0603	0603
29	R17, R34	2	57.6k	CRCW060357K6FKEA	Vishay-Dale	RES, 57.6k ohm, 1%, 0.1W, 0603	0603
30	R20	1	1.30k	CRCW06031K30FKEA	Vishay-Dale	RES, 1.30k ohm, 1%, 0.1W, 0603	0603
31	R22	1	48.7	CRCW080548R7FKEA	Vishay-Dale	RES, 48.7 ohm, 1%, 0.125W, 0805	0805
32	U1, U2	2		LM5122QMH/NOPB	Texas Instruments		20HTSSOP
33	Vin1, Vout1	2	Red	5000	Keystone	Test Point, TH, Miniature, Red	Keystone5000
34	Vin Gnd1, Vout Gnd1	2	Black	5001	Keystone	Test Point, TH, Miniature, Black	Keystone5001
35	C1, C2, C19, C21	0	470pF	GRM2165C2A471JA01D	MuRata	CAP, CERM, 470pF, 100V, +/-5%, C0G/NP0, 0805	0805
36	C16	0	100pF	GRM1885C1H101JA01D	MuRata	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	0603
37	Q2, Q6	0	80V	BSC047N08NS3 G	Infineon Technologies	MOSFET, N-CH, 80V, 100A, PG-TDSON-8	PG-TDSON-8
38	R1, R2, R19, R23	0	7.5	ERJ-12ZYJ7R5U	Panasonic	RESISTOR 7.5 OHM 3/4W 5% 2010	2010
39	R8, R28	0	0	ERJ-3GEY0R00V	Panasonic	RES, 0 ohm, 5%, 0.1W, 0603	0603
40	R9	0	158k	CRCW0603158KFKEA	Vishay-Dale	RES, 158k ohm, 1%, 0.1W, 0603	0603
41	R33	0	20.0k	CRCW060320K0FKEA	Vishay-Dale	RES, 20.0k ohm, 1%, 0.1W, 0603	0603
42	Sync In 1, Sync In 2	0	White	5002	Keystone	Test Point, TH, Miniature, White	Keystone5002

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